**Material Set Change:**

|  |  |  |
| --- | --- | --- |
| Package Material Set | Carsem | ASE Chungli |
| SOIC\_NSOIC\_WSOIC\_IC | Die Attach | Ablestik 84-1LMISR4 | Hitachi EN4900GC |
| Mold Compound  | Sumitomo 6600H or G600C | Sumitomo G700LY  |
| Wire | 1.0mil and 1.3 mil Gold Wire | 1.0mil and 1.3mil Gold Wire  |

|  |  |  |
| --- | --- | --- |
| Package Material Set | Carsem | ASE Chungli |
| SOIC\_NSOIC\_WSOIC\_IC | Die Attach | Ablestik 84-3J | Ablestik 2025D |
| Mold Compound  | Sumitomo 6600H or G600C | Sumitomo G700LY  |
| Wire | 1.0mil and 1.3 mil Gold Wire | 1.0mil and 1.3mil Gold Wire  |